



# Call for Papers – DPS 2022

## 43<sup>rd</sup> International Symposium on Dry Process

November 24(Thu) – 25(Fri), 2022

Osaka International Convention Center, Osaka, Japan

**HYBRID SYMPOSIUM**

Paper Submission Deadline: **July 22, 2022**

Author instructions and information about DPS can be found at:

<http://www.dry-process.org/2022/>



The **43<sup>rd</sup>** International Symposium on Dry Process (DPS2022) will be held at Osaka International Convention Center, Osaka, Japan & Online from November 24 to 25, 2022. DPS2022 will be a hybrid symposium that will run in-person (number of attendees limited) and virtually. The Symposium covers all aspects of the rapidly evolving fields of dry processes, including but not limited to plasma etching and deposition processes, diagnostics and modeling of plasmas and surfaces, and surface modifications by plasmas, for the applications in, e.g., microelectronics, power devices, sensors, environmental protection, biological systems, and medicine. The DPS has provided valuable forums for in-depth discussion among professionals and students working in this exciting field for more than three decades.

<Possibility of Change of Meeting Format>

Please note that DPS2022 may go fully online depending on the COVID-19 situation.

**Theme:** Dry processes and related technologies from fundamentals to applications

**Topics:**

1. Etching Technologies
2. Manufacturing Technologies (AEC, APC, EES, FDC)
3. Surface Reaction and Damage
4. Plasma Diagnostics and Monitoring Systems
5. Computational Approaches  
(Modeling, Simulation, Machine Learning, AI, Informatics, DX) for Dry Process
6. Plasma Generation (Equipment/Source)
7. Deposition Technologies (CVD / PVD)
8. Atomic Layer Processes (ALD/ALE)
9. Dry process for Green Transformation:GX  
(Energy saving technology, Alternative gas, 3D-IC/Packaging)
10. Plasma Processes for New Material Devices (MRAM, Power, Organic)
11. Plasma Processes for Biological and Medical application, MEMS
12. Atmospheric Pressure Plasma and Liquid Plasma
13. New Dry Process Concepts

**Arranged session:**

AS1 – Challenges to limits for high aspect ratio etching

AS2 – Novel control of surface reaction in atomic layer processes (ALE / ALD / Area selective ALD)

AS3 – 3D-IC packaging for energy-saving and high-density interconnection

For further general information, please contact: [e-mail:dps2022@officepolaris.co.jp](mailto:dps2022@officepolaris.co.jp)

Organizing Committee Chair: Miyako Matsui (Hitachi, Ltd.)

Executive Committee Chair: Tatsuru Shirafuji (Osaka City University)

Program Committee Chair: Yasuhiro Morikawa (ULVAC Inc.)

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**URL:** <http://www.dry-process.org/2022/>